









2025年第二季法人說明會

Investor Conference

2025.05.19





C SUN MFG., Ltd.

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Materials Management

Dec. 2024



免責聲明 Disclaimer

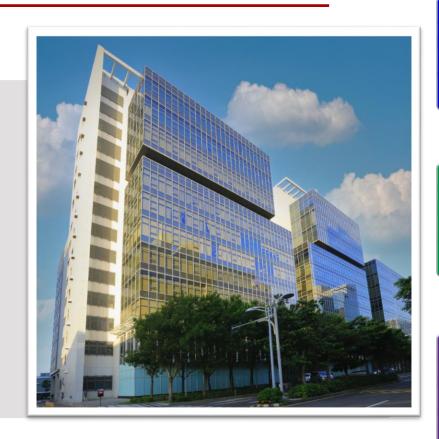
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均華精密工業股份有限公司 Gallant Micro. Machining Co., Ltd.

GMM Overview



Company History Established in 2010

2018 IPO (Stock Code : 6640)

Main Products

Advanced Packaging Pick & Place

Chip Sorter

Die Bonder

Business Locations

- Tucheng HQ
- Hsinchu
- Suzhou

- Taichung
- Kaohsiung





2025 第一季營運成果

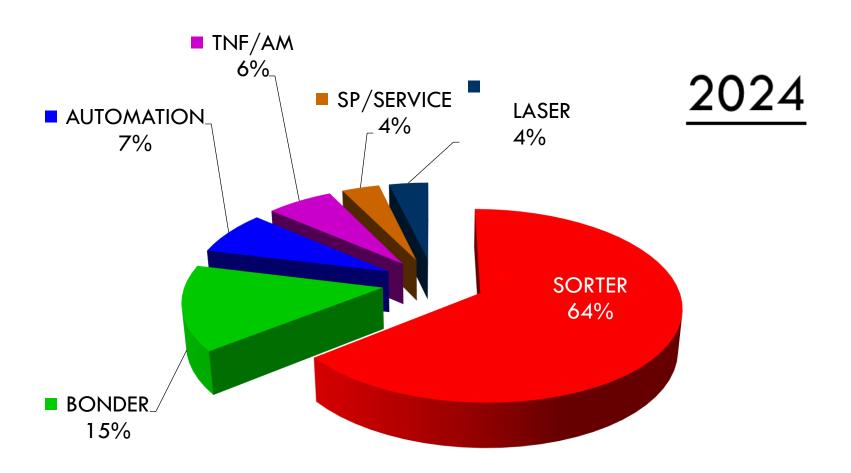
in TWD 千元

Year	2025Q1		2024		2023		2022		2021	
Accumulated	Amount	%	Amount	%	Amount	%	Amount	%	Amount	%
Revenue-Consolidated	430,220		2,441,879		1,187,852		1,482,663	_	1,482,315	·
COGS	261,777	60.8%	1,518,370	62.2%	776,443	65.4%	886,296	59.8%	978,554	66.0%
Gross Margin	168,443	39.2%	923,509	37.8%	411,409	34.6%	596,367	40.2%	503,761	34.0%
Operating Expense	115,459	26.8%	481,719	19.7%	292,573	24.6%	350,316	23.6%	342,765	23.1%
Operating Income	52,984	12.3%	441,790	18.1%	118,836	10.0%	246,051	16.6%	160,996	10.9%
Net Income before tax	55,874	13.0%	520,335	21.3%	118,350	10.0%	298,745	20.1%	200,128	13.5%
Net Income after tax	45,841	10.7%	412,772	16.9%	100,857	8.5%	229,720	15.5%	157,506	10.6%
ROE	3.15%		27.31%		8.06%		20.81%		16.06%	
EPS (NT\$/after tax)	\$1.64		\$14.62		\$3.57		\$8.33		\$5.84	
Debt Ratio	68.14%		55.42%		61.26%		54.09%		59.36%	





2024 產品銷售分析





產品發展脈絡



Bonder/ Sorter

核心技術相輔相成

Sorter 佈局

- ✓ AOI 加值
- ✓ 樂高模組
- → Sorter 市場延伸應用佔比極大化

Bonder 領軍系列產品

- ✓ EFEM、串機模組
- ✓ AOI應用

核心技術 延伸新產品

- ✓ Hybrid Bond 發展
- ✓ Jig Saw

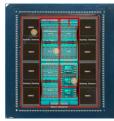


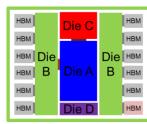
Key Value Technology

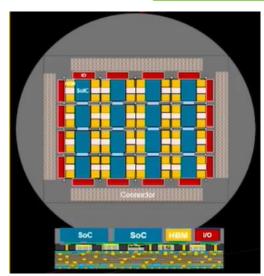


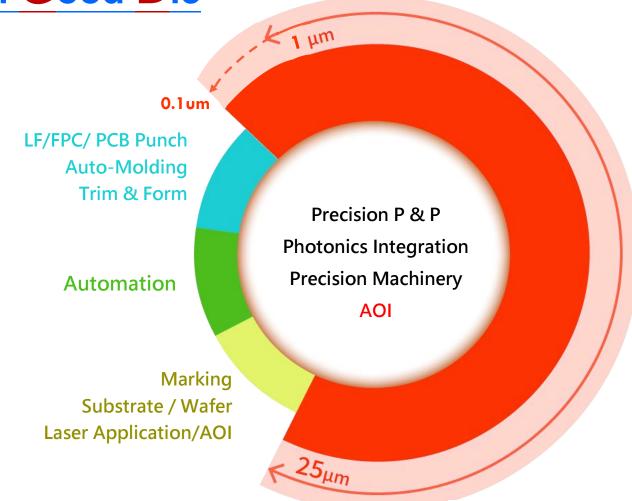
Al Sorter for Known Good Die

6S Inspection Chip Sorter









Die Attach

Die Bonder for Fan-out/ InFO/ CoWoS/ FOPLP





2025 展望

根據目前對營運前景的評估,

GMM預期受惠於先進封裝製程需求的持續擴張,

第二季營收表現可望較前一季顯著成長。



截至目前為止,尚未觀察到主要客戶在方向或策略上有明顯調整。不過,匯率變動、關稅政策等潛在外部因素,仍可能對市場需求產生一定程度的不確定性與風險。GMM將持續密切關注整體市場發展與潛在影響,並與主要客戶保持緊密合作,以共同推動成長動能。



C SU加志聖 Exhibition Preview

SEMICON*
SOLUTION
ASIA Special Edito

MAY 20-22, 2025 10:00~17:00 SGT SANDS EXPO & CONVENTION CENTRE SINGAPORE

BASEMENT 2

B1524

We sincerely invite you to visit our exhibition booth for inquiries.

Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.



Booth No.

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Invitation





G2C+ 2025

5/20-22 SEMICON SEA

(Basement B1524)

5/27-30 ECTC (Booth No. 111)

9/10-12 SEMICON TW

(Booth N0762)

10/8-9 SEMICON Kyushu

10/22-24 TPCA Show

12/17-19 SEMICON JAPAN

